BGA

LEADED MEDIUM TEMPERATURE SOLDER PASTE

Sn63/Pb37

MELTING POINT183℃

SIX CHARACTERISTICS

183°C melting point

Very little tin sticking together

Aluminum box packaging

Tin point is round and full

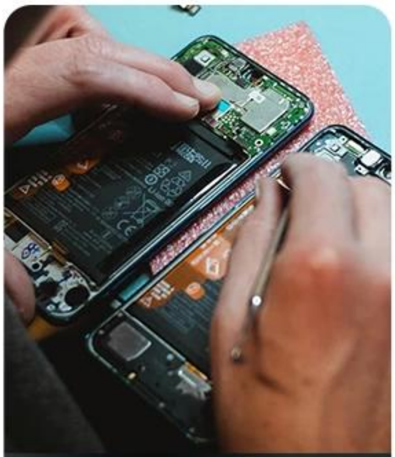
Premium quality

200 G

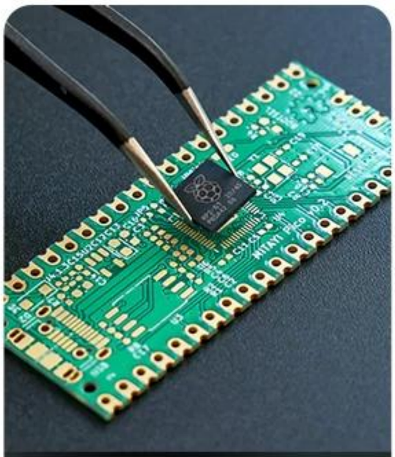
Quality Assurance Intimate Service

APPLICABLE SCOPE

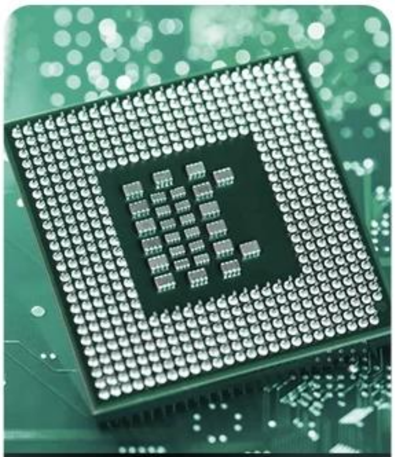
Suitable for SMT patch, BGA soldering, LED



Phone Repair



SMT Patches



BGA planting tin

LED patch

welding work

Capacitance resistance

solder paste

MODERATE VISCOSITY

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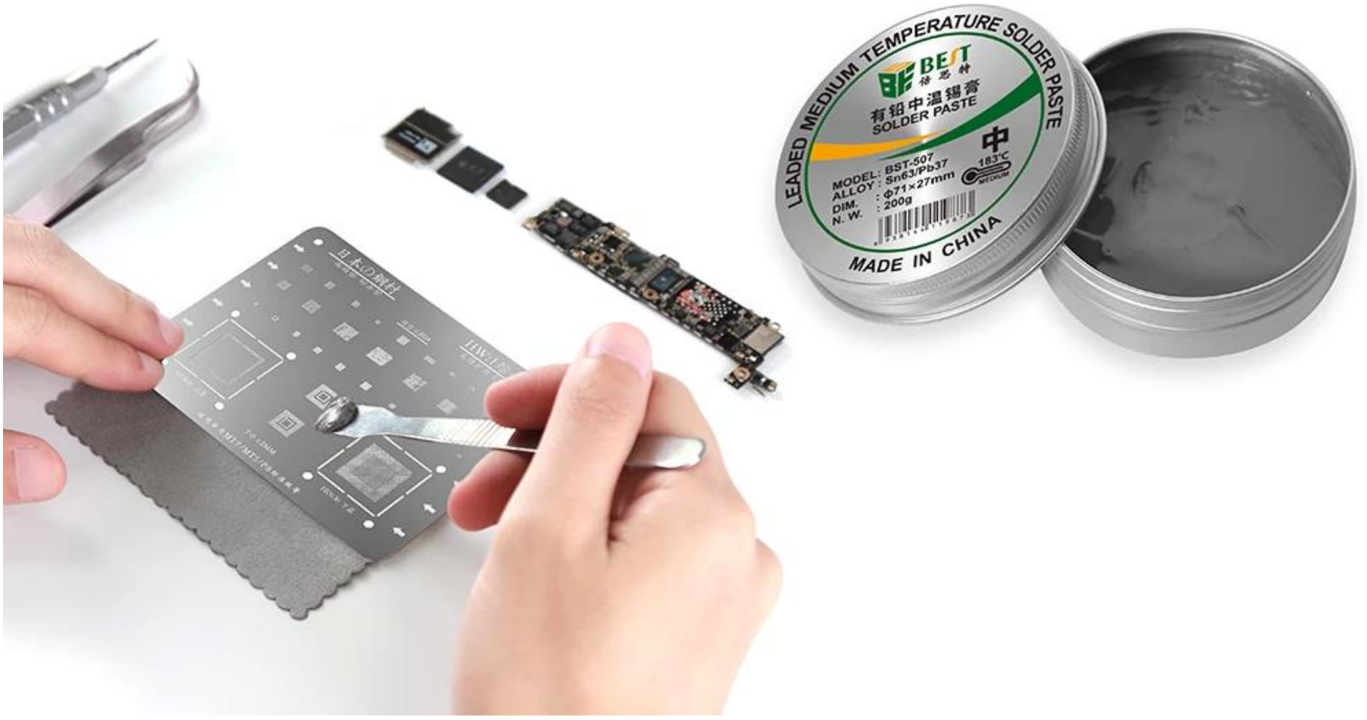
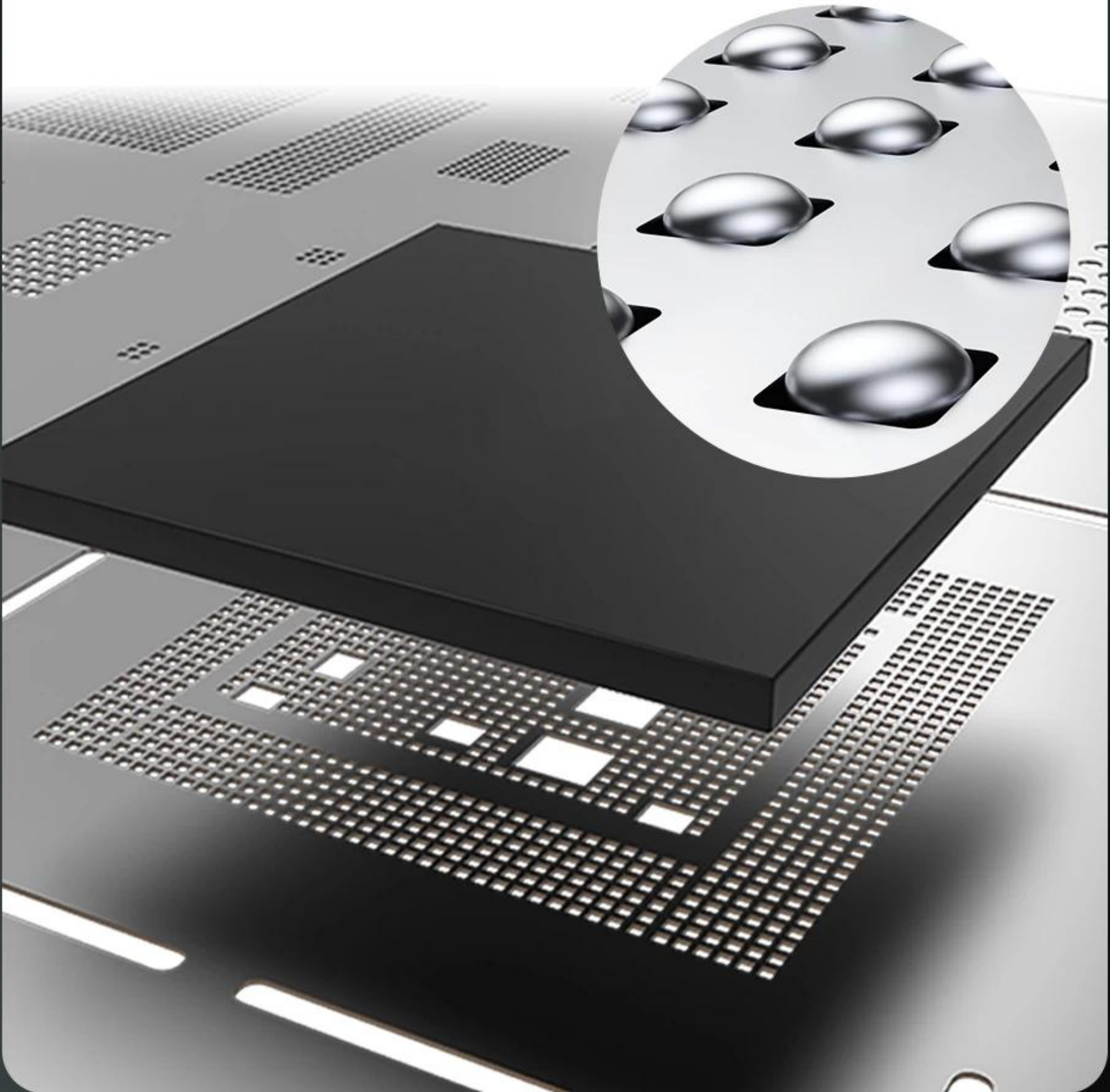
not easy to slump and deviation shift



solder paste

TIN POINT BRIGHT AND FULL

High impedance, strong activity, bright and full tin point, easy to solder
No virtual welding or false welding phenomenon



PRODUCT PARAMETERS

Name	Model	Material
Solder paste	BST-507	Sn63/Pb37
N.W.	**Package**	**Melting point**
200g	Aluminum box	183℃
Size		
70*70*30mm		

*The above dimensions are all measured by hand, if there is any error, it is within 1-3mm.

INSTRUCTIONS FOR USE

1. Usually, the solder paste should be stored in a low temperature environment.

2. Avoid placing the solder paste in the sun.

3. Before opening the package, return the solder paste to room temperature, and be careful not to use a machine for rapid heating.

4. After returning to temperature, it needs to be fully stirred before use.

5. The unused solder paste needs to be stirred again when it is used again. If it is found that the stirring cannot be started, use the special thinner for solder paste and then stir it again. After stirring evenly, it can be used again.

6. The surface of the printed board and the number of solder joints determine the amount of solder paste added to the stencil for the first time. Generally, 200-300g is added for the first time. After printing for a period of time, add a little more appropriately to ensure that the solder paste is printed. When rolling clockwise along the advancing direction of the scraper, the thickness is approximately equal to 1/2 to 3/4 of the height of the metal scraper.

7. The best working conditions of solder paste are: temperature 20~25°C,relative humidity 50~70%, clean,dust-free and anti-static.

8. When mixing new and old solder paste, use 1/4 of the old solder paste and 3/4 of the fresh solder paste to mix together evenly to keep the new and old solder paste in the best state when mixed together.

9. Do not put fresh solder paste and used solder paste into the same bottle. When removing the solder paste from the stencil, replace it with another empty bottle to prevent the fresh solder paste from being contaminated by the old solder paste

10. Precautions, if you accidentally touch your hands and feet, immediately rinse with soap and water, do not rub with your hands, and a small amount of residue can be scrubbed with alcohol.